LN52

GaAs Infrared Light Emitting Diode

For optical control systems

Features

- High-power output, high-efficiency : $P_O = 6 \text{ mW (typ.)}$
- Wide directivity, matched for external optical systems : $\theta = 100$ deg.
- Infrared light emission close to monochromatic light : $\lambda_P = 950 \text{ nm}$
- Optimum for mesuring instruments and control equipments in conbination with silicon photodetectors

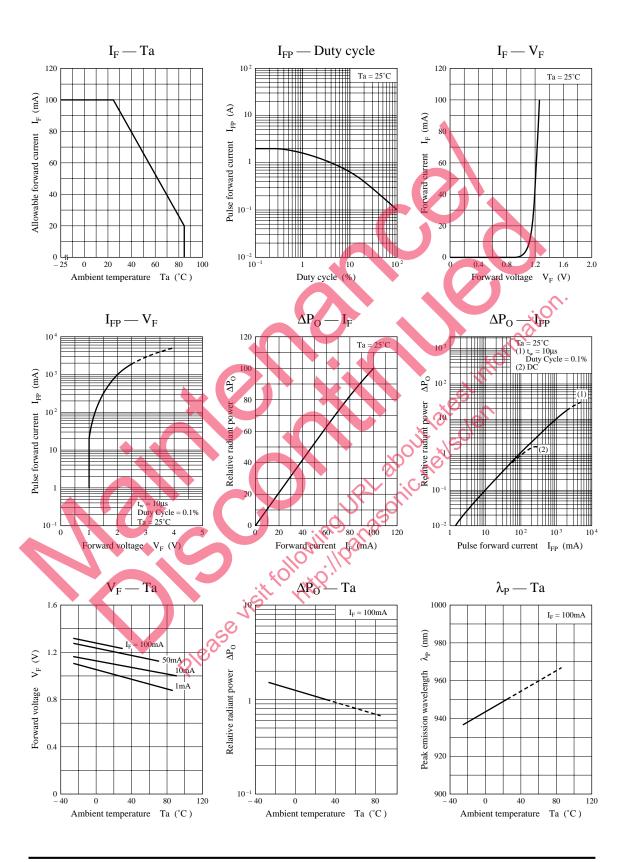
■ Absolute Maximum Ratings (Ta = 25°C)

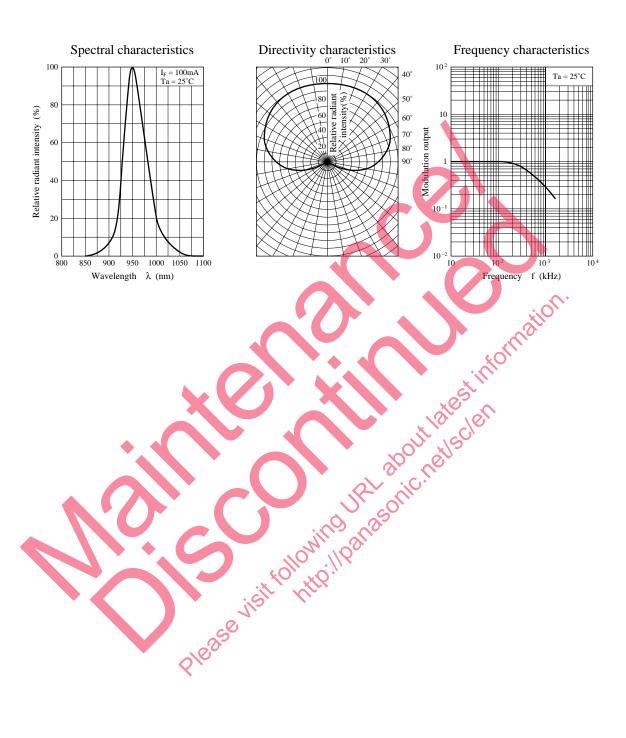
Parameter	Symbol	Ratings	Unit	
Power dissipation	P_{D}	160	mW	
Forward current (DC)	I_{F}	100	mA	
Pulse forward current	I_{FP}^*	2	A	
Reverse voltage (DC)	V_{R}	3	V	
Operating ambient temperature	T_{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

^{*} f = 100 Hz, Duty cycle = 0.1 %

■ Electro-Optical Characteristics (Ta = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Radiant power	Po	$I_F = 100 \text{mA}$	3.5	6		mW
Peak emission wavelength	$\lambda_{ m P}$	$I_{\rm F} = 100 \text{mA}$		950		nm
Spectral half band width	Δλ	$I_F = 100 \text{mA}$		50		nm
Forward voltage (DC)	VFO	$I_F = 100 \text{mA}$		1.25	1.6	V
Reverse current (DC)	$\mathcal{O}\mathbf{I}_{R}$	$V_R = 3V$			10	μΑ
Capacitance between pins	C _t	$V_R = 0V$, $f = 1MHz$		50		pF
Rise time	t _r	$I_{EP} = 100 \text{mA}$		1		μs
Fall time	t _f	IFP — TOOIIIA		1		μs
Half-power angle	θ	The angle in which radiant intencity is 50%		100		deg.







■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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